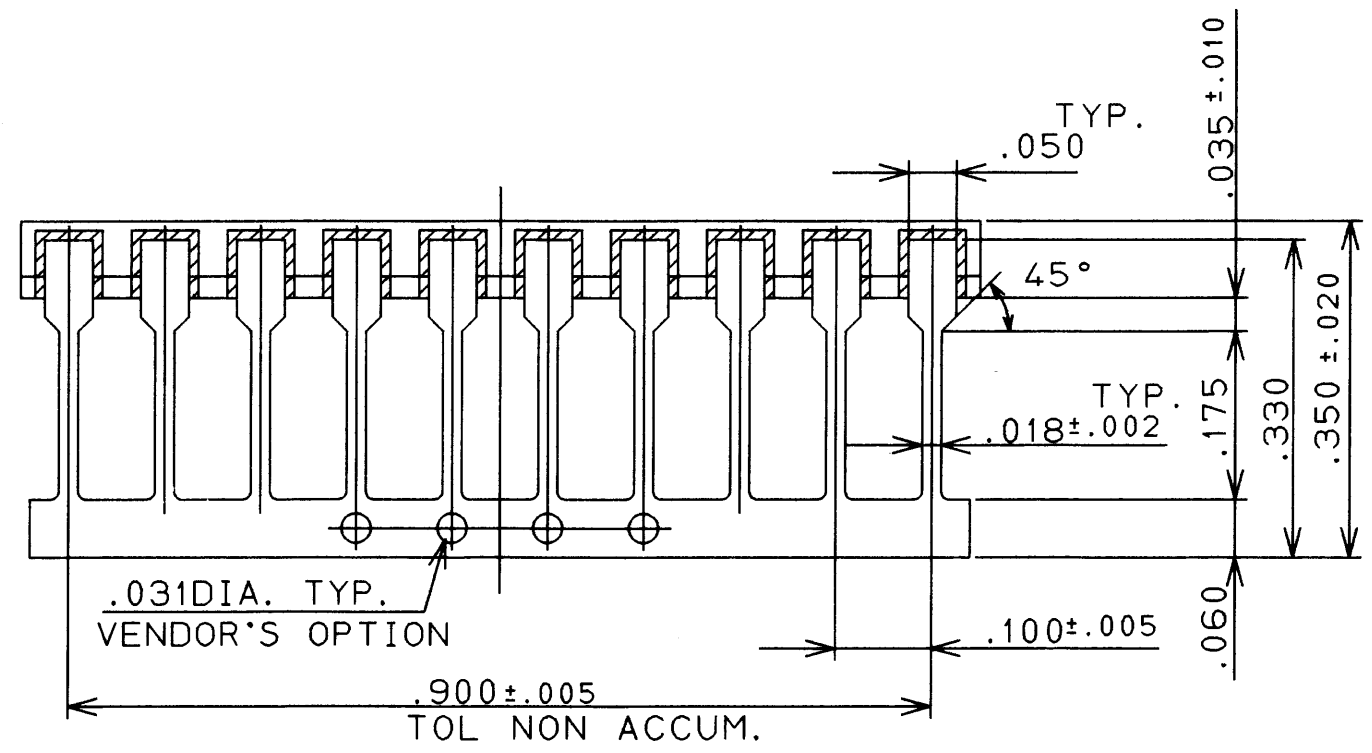


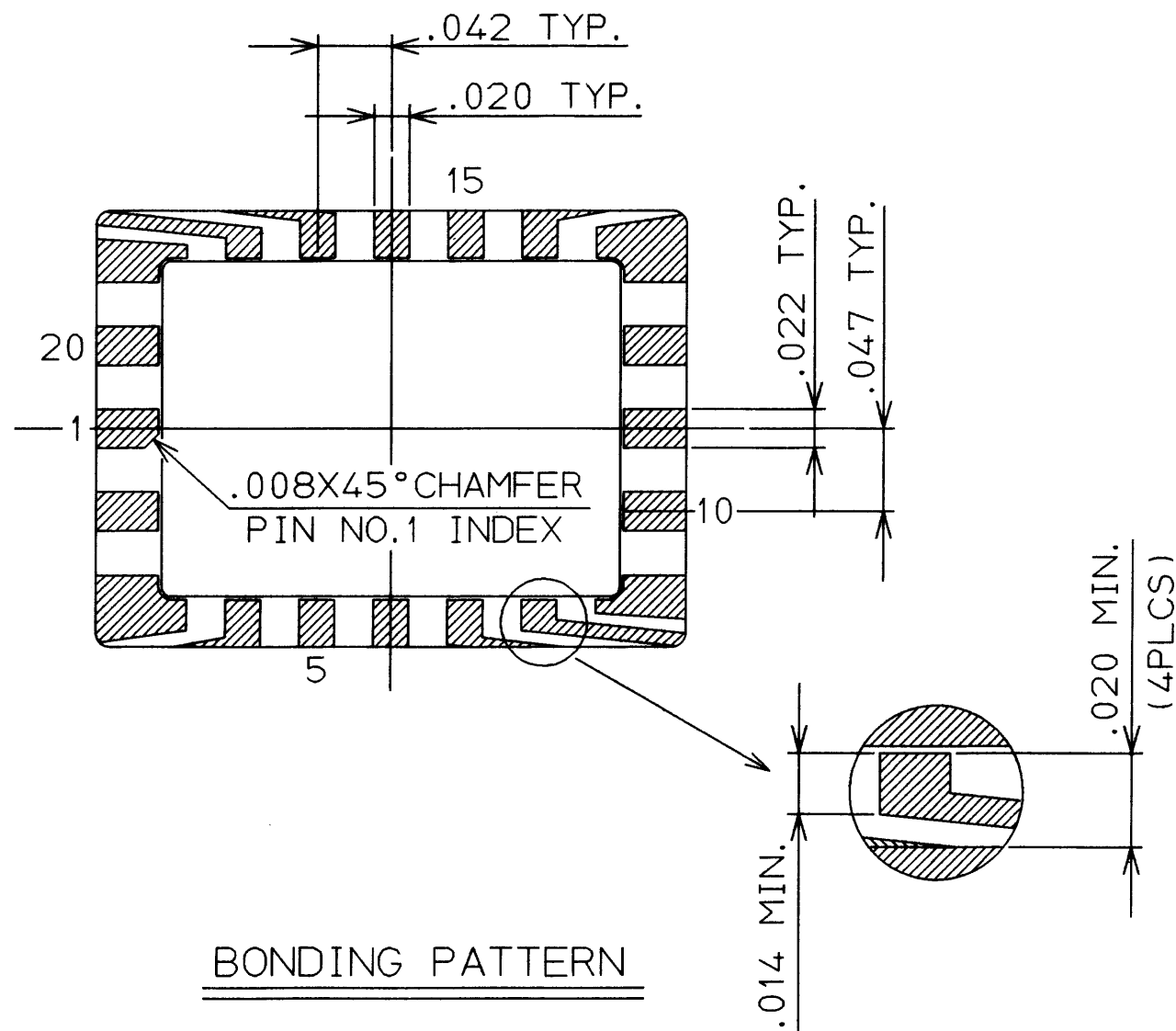
- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.30 Ω MAX.



SB020R546-1 S=0 D=0

MODIFICATION					NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005	DRAWN S.F	CHECKED T.A	APPROVED	DATE MAY.23.'85
					SCALE 5/1	MATERIAL AS INDICATED	THIRD ANGLE PROJECTION			
	REDRAWN: (CAD DATA) CHANGED	MAR.17.'92	DATE	DRAWN 	CHECKED 	APPROVED 	DRAWING NO. KD-S85546-B		SHEET 1/2	

KYOCERA CORPORATION
KYOTO JAPAN



MODIFICATION						NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN S.F	CHECKED T.A	APPROVED —	DATE MAY.23.'85
						SCALE 10 / 1	MATERIAL —	THIRD ANGLE PROJECTION			
	REDRAWN: (CAD DATA)	MAR.17.'92	<i>W. de Bie</i>	<i>S. P. J. J. J.</i>			KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		KD-S85546-B	SHEET 2/2
	CHANGED	DATE	DRAWN	CHECKED	APPROVED						